

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
BIN WU	09/11/2020
<b>RECEIVING PARTY DATA</b>	
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<b>State/Country:</b>	CHINA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17044316
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<b>SIGNATURE:</b>	/Raymond J. Chew/
<b>DATE SIGNED:</b>	09/30/2020
<b>Total Attachments: 2</b>	
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**ASSIGNMENT**

BIN WU having a mailing address H1 BUILDING, HONGFA HI-TECH INDUSTRIAL PARK, TANGTOU COMMUNITY, SHIYAN STREET, BAO'AN DISTRICT, SHENZHEN, GUANGDONG, CHINA (hereafter referred to as the undersigned), is the inventor of the U.S. patent application to be filed entitled:

**QUICK-CONNECT MODULAR LED LAMP STRIP**

The above U.S. application was assigned serial no. \_\_\_\_\_ and was filed on \_\_\_\_\_. The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

SHENZHEN SHINESKY OPTOELECTRONICS CO., LTD Having a place of business H1 BUILDING, HONGFA HI-TECH INDUSTRIAL PARK, TANGTOU COMMUNITY, SHIYAN STREET, BAO'AN DISTRICT, SHENZHEN, GUANGDONG, CHINA (hereafter referred to as the assignee), is desirous of the entire right, title and interest in the above-identified application, in said invention described therein, all applications for and all letters patent issued on said invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in said invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, in any subsequent nonprovisional applications filed for this invention or improvements thereto, and all divisions and continuations thereof, any Registered Community Design applications, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of said invention, to testify

Attorney Docket No.: **ZH-1US0025**  
Customer No.: 128477

in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrant that the rights and property herein conveyed are free and clear of any encumbrance. EXECUTED under seal on the following date 09/11/2020

Typed or printed name	Signature
<u>BIN WU</u>	<u>BIN WU</u>